Bluetooth Module Datasheet

Model: SJR-BTM571

Version: V1.0

2022-03-03

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1 Introduction

Sky Jiarun Technologies introduces the pioneer of the Bluetooth 5.3 modules SJR-BTM571 which is a high performance, cost effective, low power and compact solution. The Bluetooth module provides a complete 2.4GHz Bluetooth system based on the QCC5171 WLCSP chipset which is a single chip radio and baseband IC for Bluetooth 2.4GHz systems. This module is fully qualified single-chip dual mode Bluetooth@v5.3 system.

2 Key Features

BTM571(QCC5171) Features

- Qualified to Bluetooth v5.3 specification
- Dual 240 MHz Qualcomm® Kalimba[™] audio DSP
- 32/80 MHz Developer Processor for applications
- Firmware Processor for system
- Flexible QSPI flash programmable platform
- High-performance 24-bit stereo audio interface
- Digital and analog microphone interfaces
- Flexible PIO controller and LED pins with PWM support
- Serial interfaces: UART, Bit Serializer (I² C/SPI), USB 2.0
- Advanced audio algorithms
- Active Noise Cancellation:Hybrid, Feedforward, and Feedback modes, using Digital or Analog Mics, enabled using license keys available from Qualcomm®
- Qualcomm[®] aptX[™] and aptX HD Audio
- aptX Adaptive, enabled using license key
- Qualcomm® cVc[™] Noise Cancellation Technology,enabled using license key
- Integrated PMU: Dual SMPS for system/digital circuits, Integrated Li-ion battery charger

Application subsystem

- Dual-core application subsystem 32/80MHz operation
- 32-bit Firmware Processor (reserved for system use) executes:
 - Bluetooth upper stack
 - Profiles
 - House-keeping code
- 32-bit Developer Processor executes:
 - Developer applications
- Both cores execute code from external flash memory using QSPI clocked at 32 MHz or 80 MHz
- On-chip caches per core enable optimized performance and power consumption

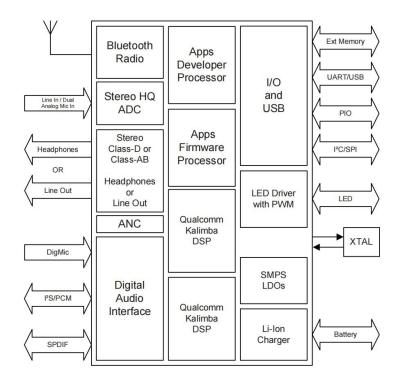
Bluetooth subsystem

- Qualified to Bluetooth v5.3 specification including 2 Mbps Bluetooth Low Energy and Bluetooth Low Energy Isochronous Channels
- Qualcomm[®] Bluetooth High Speed Link
- Single ended antenna connection with on-chip balun and Tx/Rx switch
- Bluetooth, Bluetooth Low Energy, and mixed topologies supported
- Class 1 support

3 Applications

- Wired/wireless stereo headsets/headphones
- Qualcomm TrueWireless[™] stereo earbuds

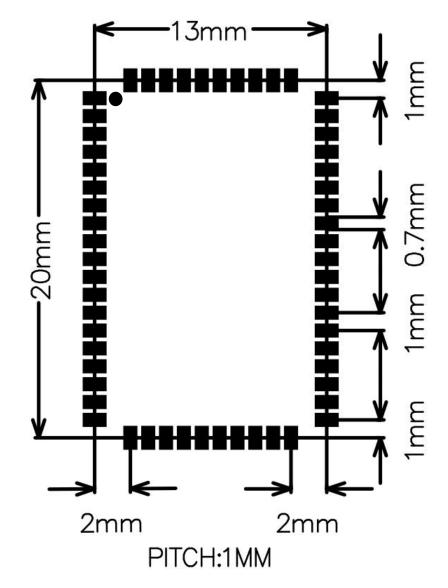
4 Block Diagram



5 General specifications

Model Name	SJR-BTM571	
Product Description	Bluetooth 5.3 Class1.5 Module	
Bluetooth Standard	Bluetooth 5.3	
Chipset	QCC5171 WLCSP	
Dimension	13mm x 20mm x 2.8mm	
Operating Conditions		
Voltage	2.8~4.3V	
Temperature	-40∼+85℃	
Storage Temperature	-40∼+85 ℃	
Electrical Specifications		
Frequency Range	2402~2480MHz	
Maximum RF Transmit Power	13dBm	
π /4 DQPSK Receive Sensitivity	-94dBm	
8DPSK Receive Sensitivity	-88dBm	

6 Module Package Information

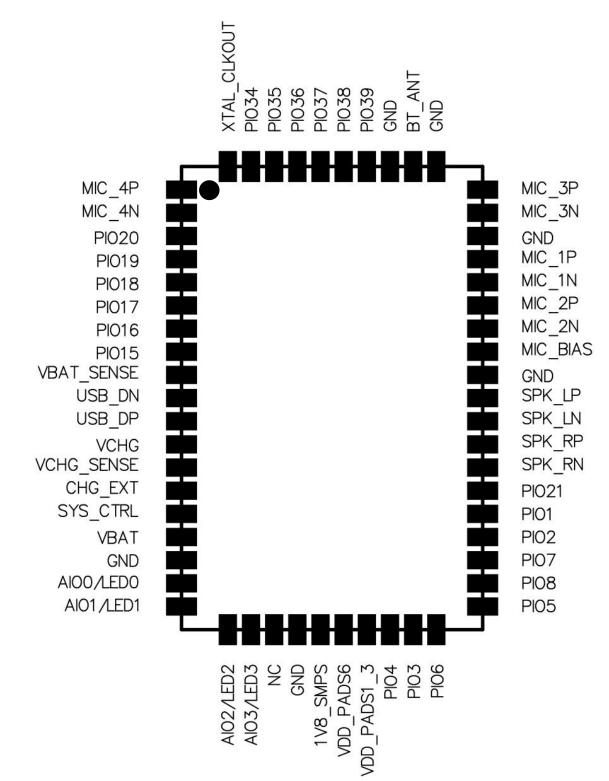


6.1 Pinout Diagram and package dimensions



Recommended PCB layout footprint

6.2 Module Pin descriptions



Pin#	Pin Name	Pin type	Description
			Microphone differential 4 input, positive.
1	MIC_4P	Analog	Alternative function:
	_	5	 Differential audio line input 4,positive
			Microphone differential 4 input, negative.
2	MIC_4N	Analog	Alternative function:
	_	5	Differential audio line input 4,negative
		Digital: Bidirectional with	Programmable I/O line 20.
3	PIO[20]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ PCM_DOUT[1]
		Digital: Bidirectional with	Programmable I/O line 19.
4	PIO[19]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ PCM_DIN[0]
		Digital: Bidirectional with	Programmable I/O line 18.
5	PIO[18]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ PCM_DOUT[0]
		Digital: Bidirectional with	Programmable I/O line 17.
6	PIO[17]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ PCM_SYNC
		Digital: Bidirectional with	Programmable I/O line 16.
7	PIO[16]	programmable strength	Alternative function:
		internal pull-up/pull-down	PCM_CLK
		Digital: Bidirectional with	Programmable I/O line 15.
8	PIO[15]	programmable strength	Alternative function:
		internal pull-up/pull-down	MCLK_OUT
9	VBAT_SENSE	Analog	Battery voltage sense input.
10	USB_DN	Digital	USB Full Speed device D- I/O.
11	USB_DP	Digital	USB Full Speed device D+ I/O.
12	VCHG	Supply	Supply to SMPS power switch from battery.
			Charger input sense pin. High
13	VCHG_SENSE	Analog	impedance. Connect VCHG_SENSE
	_		direct to SMPS_VCHG.
			External charger transistor current
			control. Connect to base of external
14	CHG_EXT	Analog	charger transistor as per application
			schematic.
			Typically connected to an ON/OFF push
			button. If power is present from the
			battery and/or charger, and software has
			placed the device in the OFF or
15	SYS_CTRL	Digital input	DORMANT state, a button press boots
			the device. Also usable as a digital input
			in normal operation. No pull.
			Additional function:
			 PIO[0] input only

16	VBAT	Supply	Battery voltage input.
17	GND	Ground	Ground
		Analog or digital input/	General-purpose analog/digital input or
18	8 AIO0/LED0	open drain output.	open drain LED output.
		Analog or digital input/	General-purpose analog/digital input or
19	9 AIO1/LED1	open drain output.	open drain LED output.
		Analog or digital input/	General-purpose analog/digital input or
20	AIO2/LED2	open drain output.	open drain LED output.
		Analog or digital input/	General-purpose analog/digital input or
21	AIO3/LED3	open drain output.	open drain LED output.
22	NC	NC	NC
23	GND	Ground	Ground
24	1V8_SMPS	Supply	1.8V voltage output.
25	VDD_PADS6	Supply	1.8 V/3.3 V PIO supply.
26	VDD_PADS1_3	Supply	1.8 V/3.3 V PIO supply.
		Digital: Bidirectional with	Programmable I/O line 4.
27	PIO[4]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ TBR_MOSI[1]
		Digital: Bidirectional with	Programmable I/O line 3.
28	PIO[3]	programmable strength	Alternative function:
	- [-]	internal pull-up/pull-down	■ TBR_MISO[2]
		Digital: Bidirectional with	Programmable I/O line 6.
29	PIO[6]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ TBR_MOSI[0]
		Digital: Bidirectional with	Programmable I/O line 5.
30	PIO[5]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ TBR_MISO[1]
		Digital: Bidirectional with	Programmable I/O line 8.
31	PIO[8]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ TBR_CLK
		Digital: Bidirectional with	Programmable I/O line 7.
32	PIO[7]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ TBR_MISO[0]
		Digital: Bidirectional with	Programmable I/O line 2.
33	PIO[2]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ TBR_MISO[3]
			Automatically defaults to
			RESET# mode when the device is unpowered, or in
34	PIO[1]	Digital: Bidirectional with	off modes.
		programmable strength	Reconfigurable as a PIO after boot.
		internal pull-up/pull-down	Alternative function:
			■ Programmable I/O line 1
		Digital: Bidirectional with	Programmable I/O line 21.
35	PIO[21]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ PCM_DOUT[2]

			Headphone/speaker differential 2
36	SPK_RN	Analog	output, negative.
30		Analog	Alternative function:
			Differential line output 2, negative
			Headphone/speaker differential 2
07			output, positive.
37	SPK_RP	Analog	Alternative function:
			 Differential line output 2, positive
			Headphone/speaker differential 1
00			output, negative.
38	SPK_LN	Analog	Alternative function:
			 Differential line output 1, negative
			Headphone/speaker differential 1
			output, positive.
39	SPK_LP	Analog	Alternative function:
			 Differential line output 1, positive
40	GND	Ground	Ground
41	MIC_BIAS	Analog	Mic bias output.
			Microphone differential 2 input,
			negative.
42	MIC_2N	Analog	Alternative function:
			 Differential audio line input 2,
			negative
			Microphone differential 2 input, positive.
40			Alternative function:
43	MIC_2P	Analog	 Differential audio line input 2,
			positive
			Microphone differential 1 input,
			negative.
44	MIC_1N	Analog	Alternative function:
			 Differential audio line input 1,
			negative
			Microphone differential 1 input, positive.
	MIC_1P		Alternative function:
45		Analog	 Differential audio line input 1,
			positive
46	GND	Ground	Ground
			Microphone differential 3 input,
			negative.
47	MIC_3N	Analog	Alternative function:
	_		 Differential audio line input 3,
			negative
			Microphone differential 3 input, positive.
48	MIC_3P	Analog	Alternative function:
-			 Differential audio line input 3,

			positive
49	GND	Ground	Ground
50	BT_ANT	RF	Bluetooth transmit/receive.
51	GND	Ground	Ground
		Digital: Bidirectional with	Programmable I/O line 39.
52	PIO[39]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ QSPI2_IO[3]
		Digital: Bidirectional with	Programmable I/O line 38.
53	PIO[38]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ QSPI2_CS0#
		Digital: Bidirectional with	Programmable I/O line 37.
54	PIO[37]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ QSPI2_IO[1]
		Digital: Bidirectional with	Programmable I/O line 36.
55	PIO[36]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ QSPI2_IO[2]
		Digital: Bidirectional with	Programmable I/O line 35.
56	PIO[35]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ QSPI2_CLK
		Digital: Bidirectional with	Programmable I/O line 34.
57	PIO[34]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ QSPI2_IO[0]
58	XTAL_CLKOUT	Analog	Buffered clock output.

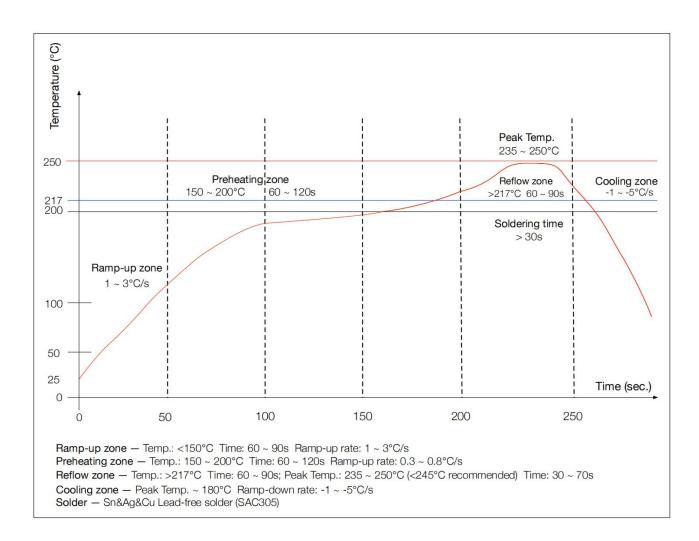
7 Electrical Characteristics

7.1 Absolute Maximum Ratings

Rating	Minimum	Maximum
Storage temperature	-40 ℃	+85 ℃

7.2 Recommended Operating Conditions

Operating Condition	Minimum	Maximum
Operating temperature range	-40 ℃	+85 ℃
Supply voltage: VBAT	+2.8V	+4.3V



8 Recommended reflow temperature profile

The module Must go through 125 $^\circ\!\mathrm{C}$ baking for at least 9 hours before SMT AND IR reflow process!

若拆封后未立即上线, 天嘉润科技建议让下次上线前务必以 125℃烘烤 9 小时以上!

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Data	Revision	Description
2022-03-03	V1.0	Original publication of this document.

Record of Changes

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